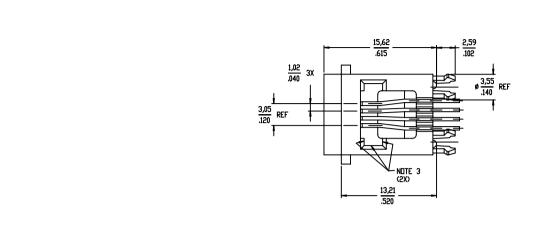
PRODUCT NO

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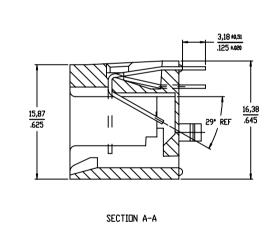
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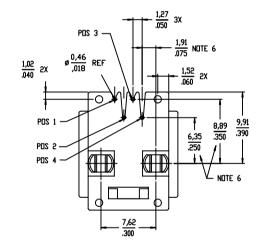
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Α

CONTACT PLATING

GXT

30u" / ,76u Au

POSITIONS

LOADED

ALL

ALL

REMARKS

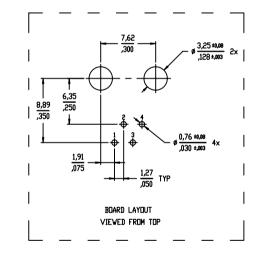
NOT TOOLED

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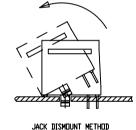
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PRODUCT NO.	POSITIONS Loaded	CONTACT PLATING	NOTES								
90511-001 -001LF -001HLF	ALL	GXT	BLACK								
-002 -002LF -002HLF	ALL	30u* / ,76u Au	BLACK	(11)							
-003 -003LF	ALL	GXT	GREY								
-004 -004LF	ALL	30u* / ,76u Au	GREY	(1)							
-005 -005LF -005 <u>HL</u> F	ALL	50u* / 1,27u Au	BLACK								
LEAD FREE PRODUCT NO.											

└─ MEETS PIP PROCESS PRODUCT NO.



DIRECTION OF DISMOUNT



DETAIL A NOTE 5

NOTES :

PRODUCT NO.

90511-101 -101LF

(11)

-101HLF -102

-102LF

-102HLF

- P/NO WITH DASH OXX -NORMAL WAVE SOLDERING APPLICATION. P/NO WITH DASH 1XX -1R REFLOW APPLICATION (NOT TOOLED).
- PACKAGING SPEC. BUS-14-164.
- SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
- JACK IS FOR 1,57/,062 THICK PCB.
- SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB, PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, DTHERWISE LEG BREAKAGE MAY DCCUR.
- THESE DIMENSIONS ARE TAKEN FROM THE TOP OF THE PEG.
- GXT IS 0,76um / 30u' MIN GXT WITH AU FLASH DVER 1,27 um /
- THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
- IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.
- EQUIVALENT THICKNESS AU AND GXT PLATING HAVE SAME FUNCTION AND THEY ARE ALTERNATIVE BY THE CUSTOEMR

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									.000	±	0.05	<u> </u>	1 <del>                                     </del>											- 1
							angle	s		± 2°			7				PCB III MOD JACK					ASSI		
					dr	М	M CHENG			7/13/01		, MM		product family MDDJACK					CO	de				
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PDM: Rev:N 3 STATUS: Released Printed: Aug 01, 2010